

BigTwin SuperServer SYS-621BT-HNC8R



More details here

Key Applications

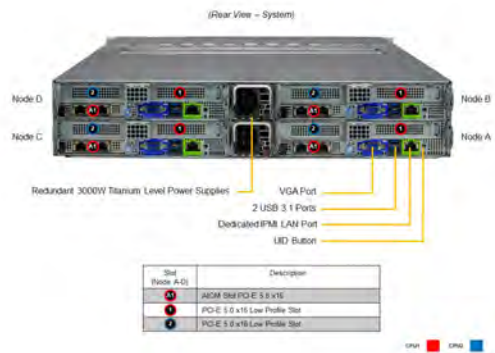
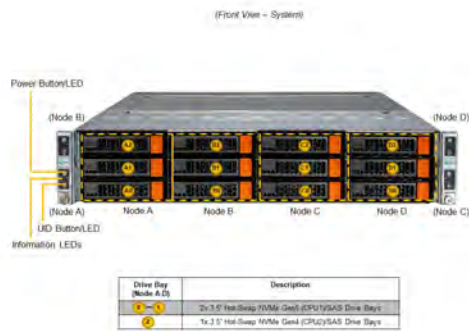
Hyperconverged Infrastructure, Scale-Out File Storage, Container Storage,

Key Features

- Socket E (LGA 4677) support 4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- Up to 16 DIMMs ECC DDR5 Slots;
- 2 PCIe 5.0 x16 (LP) slot; Tool-less support; Optional M.2 NVMe Boot Controller via SCC-A2NM2241G3-B1; Internal PCIe 5.0 x8 for 2 M.2 NVMe support onboard;
- Network connectivity via AIOM (OCP 3.0 compliant);
- 3 hot-swap 3.5" drive bays (2x PCIe 5.0 NVMe and 1x PCIe 4.0 NVMe/SAS); Built-in SAS3 Support via Broadcom 3808; IT Mode;
- Liquid Cooling Support; 4 cooling fans per 2U enclosure, 14.9K RPM; Shared Cooling Design;
- 3000W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



Form Factor	2U Rackmount Enclosure: 449 x 88 x 774mm (17.68" x 3.47" x 30.5") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA 4677 (Socket E) supported Intel Xeon CPU Max Series with high bandwidth memory (HBM) (Supports up to 350W TDP CPUs (Liquid Cooled), Supports up to 300W TDP CPUs (Aircooled), CPUs (air cooled) with TDP over 185W are only supported under specific conditions. Contact customer support for details.)
Drive Bays	3x 3.5" hot-swap NVMe/SAS drive bays; Optional HBA support via SAS3808 Adapter
Expansion Slots	2 PCIe 5.0 x16 LP slot(s)
On-Board Devices	SAS: SAS3 (12Gbps) via Broadcom® 3808 (IT mode) Chipset: Intel® C741 Network Connectivity: Via AIOM IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 3.1 port(s) (2 rear) Video: 1 VGA port(s) Others: 2x M.2 for boot drive or caching M.2 form factor: NVMe double-sided 22x110mm Note: Enterprise-grade M.2 only for caching application



System Cooling	4x 14.9K RPM Heavy Duty 8cm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	3000W 1U Redundant Power Supply Dimension (W x H x L): 45 x 40 x 480 mm
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperDoctor® 5; Watch Dog; SUM; IPMI 2.0; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; SuperCloud Composer; Supemicro Out of Band (OOB) License (Included per Node)
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Height: 3.47" (88 mm) Width: 17.68" (449 mm) Depth: 30.5" (774 mm) Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Packaging: 9.76" (H) x 24.65" (W) x 45.28" (D) Available Color: Black front & silver body
Operating Environment	ROHS: RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (Non-Condensing) Non-operating Relative Humidity: 5% to 95% (Non-Condensing)
Motherboard	Super X13DET-B
Chassis	CSE-827BQ2-R3K04P